Panasonic

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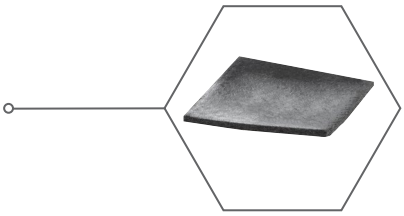
New Product Introduction

Introducing The New EYG-T Series "Graphite-PAD" Thermal Interface Material From Panasonic



High Thermal Conductivity In The Z-Direction With Superior Flexibility

Panasonic, a worldwide leader in Thermal Management Products, is pleased to introduce **NEW EYG-T Series "Graphite-PAD"**. This new addition to Panasonic's line of Thermal Management solutions is a thermal interface material that compatibly obtains excellent thermal conductivity in Z-axis thickness direction along with providing superior flexibility. The new **Graphite-PAD** product provides properties that are greater than that of most existing thermal interface materials.

Graphite-PADs are composed of silicone resin and Pyrolytic Graphite Sheets (PGS) as filler. This combination of materials offers high Thermal Management reliability by enabling designs with high heat dissipation. The PGS inside the resin is oriented in a vertical direction. This oriented structure provides excellent thermal conductivity in thickness direction. The component is very flexible (deformable) since it is mainly composed of silicone resin. Being deformable with a low load facilitates installation.

Features

- Excellent Thermal Conductivity In Z-axis Thickness Direction
- Thermal Conductivity Of The Material: 13 W/m•K
- Excellent Flexibility
- Thickness Range: 0.5 to 3.0 mm
- Hardness: TYPE E 25
- Excellent Compressibility: 50% (t=2 mm, Pressure 300 kPa)
- Tackiness: Material Holds Onto Surface Or Component
- High Reliability: Corresponds To -40°C to 150°C and Maintains Long-Term Reliability
- RoHS Compliant

Benefits

- Can Be Bent And Used On Curved Surfaces
- Compressibility Up To Almost 60%
- Tackiness On Both Sides Of The Pad Due To The Silicone Resin Holds The Material Onto A Surface Or Component
- Improved Thermal Conductivity In Thickness Direction Is Obtained By Having PGS Graphite Sheet® Oriented In Vertical Direction Filled Into Silicon Resin
- Provides Efficient Heat Conduction Thanks To Its High Adhesion Performance Generated From Flexibility. Flexibility Also Provides Degree Of Freedom In Design Because The Component Can Be Set Onto Heat Sources With A Low Load

Industries

- Power
- Audio / Visual
- Communications

Applications

- For The Cooling / Heat Transfer of Electronic Devices That Generate Heat
- Micro Inverters, IGBT Modules, FETS
- Converters
- Radio Devices, Touch Panels, Cameras
- Automotive LED
- Medical Equipment
- Motor Control Unit
- Optical Transceivers

TM THERMAL MANAGEMENT

RoHS COMPLIANT